

AMENDMENTS TO THE SPECIFICATION:

Please amend the specification as follows:

Page 52, replace the paragraph beginning on line 3 with the following amended paragraph:

In Figures 10A and 10B, the glass wafer 61 has the groove 61a corresponding to the arrangement of the chips cut from the silicon wafer 51 formed thereon, where the width of the groove 61a is set to overlap with an area having the piezoresistors 52 formed thereon equivalent to one chip and the scribe line. For instance, if the length of the tilt sensor equivalent to one chip is 3 mm, the width of the groove ~~[[21a]]~~ 61a is set at 2.5 mm.

Page 80, replace the paragraph beginning on line 20 with the following amended paragraph:

Thus, it is possible to provide the weight member while keeping the piezoresistors R21, R22 in the state capable of deflection without selectively etching the backside of the silicon substrate 21 ~~having~~ forming the piezoresistors R21, R22 formed therein.

Page 88, replace the paragraph beginning on line 1 with the following amended paragraph:

The piezoresistors R12 and R13 are arranged in the positions symmetric with respect to the center line A1 to A1, which are the same positions as the piezoresistors R11 and R14 in the lateral direction of the silicon substrate 102 and closer to the weight member 104 than the piezoresistors R11 and R14. The piezoresistors R22 and R23 are arranged in the positions symmetric with respect to the center line A1 to A1, which

are the same positions as the piezoresistors R21 and R24 in the lateral direction of the silicon substrate **[[2]] 102** and closer to the weight member 104 than the piezoresistors R21 and R24.

Page 115, replace the paragraph beginning on line 7 with the following amended paragraph:

Thus, according to this embodiment, the silicon substrate 102 having the piezoresistors formed on its surface, the support member 101b for supporting the silicon substrate 102 at one end of the silicon substrate 102, the weight member 104 arranged at the end 102b of the silicon substrate 102, and the tilt angle calculating section for calculating the tilt angles ϕ and η are provided. The piezoresistors R51 and R54 and the piezoresistors R52 and R53 are arranged in the positions symmetric with respect to the center line A1 to A1 so as to constitute the full bridge circuit C5 with R51, R52, R53 and R54 and constitute the full bridge circuit C6 of which connections are different from the full bridge circuit C5 with the piezoresistors R51, R52, R53 and R54. And the tilt angle calculating section calculates the tilt angle η based on the output voltage **[[Vo3]] Vo5** of the full bridge circuit **[[C3]] C5** and calculates the tilt angle ϕ based on the output voltage **[[Vo4]] Vo6** of the **[[half]] full** bridge circuit **[[C4]] C6** and the calculated tilt angle η .